

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
ICAM		Aluminium (Al)	7429-90-5	0	12.36	0.12
Subtotal				0	12.36	0.12
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.04	65.0	3.06
	Lead alloy	Silver (Ag)	7440-22-4	0.02	25.0	1.18
	Lead alloy	Antimony (Sb)	7440-36-0	0.01	10.0	0.47
Subtotal				0.07	100	4.71
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.46
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	4.86
	Copper alloy	Copper (Cu)	7440-50-8	66.22	99.87	4849.69
Subtotal				66.31	100	4856.01
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.33	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.98	15.0	364.5
	Filler	Silica fused	60676-86-0	24.55	74.0	1798.2
	Flame retardant	Metal hydroxide		2.32	7.0	170.1
Subtotal				33.18	100	2430
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.41	100.0	30
Subtotal				0.41	100	30
Die		Silicon Carbide (SiC)	409-21-2	0	0.0	0
Subtotal				0	0	0
Total				99.97	100	7320.84

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